



150KHz 2A PWM Buck DC/DC Converter

Product Description

The GS5220 series are monolithic IC designed for a step-down DC/DC converter, and own the ability of driving a 2A load without external transistor. Due to reducing the number of external component, the board space can be saved easily. The external shutdown function can be controlled by logic level and then come into standby mode. The internal compensation makes feedback control have good line and load regulation without external design. Regarding protected function, thermal shutdown is to prevent over temperature operating from damage, and current limit is to prevent over current operating of the output switch. If current limit function occurred and VFB is down to 0.5V below, the switching frequency will be reduced.

The GS5220 series operate at a switching frequency of 150KHz thus allowing smaller sized filter components than what would be needed with lower frequency switching regulators. Other features include a guaranteed +4% tolerance on output voltage under specified input voltage and output load conditions, and +15% on the oscillator frequency. The output version included fixed 3.3V, 5V and an adjustable type. The packages are available in a standard 5-lead TO-220, a 5-lead TO-263 or 8-lead PDIP, 8-lead SOP-8.

Features

- Output voltage:3.3V, 5V and adjustable output version
- Adjustable version output voltage range, 1.23V to 18V±4%
- 150KH_Z ±15% fixed switching frequency
- Voltage mode non-synchronous PWM control
- Thermal-shutdown and current-limit protection
- ON/OFF shutdown control input
- Operating voltage can be up to 22V
- Output load current:2A
- TO220-5L, TO263-5L, PDIP-8 and SOP-8 packages
- Low power standby mode
- Built-in switching transistor on chip

Applications

- Simple High-efficiency step-down regulator
- On-card switching regulators
- Positive to negative converter





Packages & Pin Assignments

GS5220 (PDIP-8L)			GS5220	(SOP-	8)	GS5220(TO-263-5L)		GS5220(TO-220-5L)		-5L)					
8 7 6 5 0 0 0 GS5220P-xxF 0 1 2 3 4			8 7 6 5 GS5220S-xxF 0 1 2 3 4		GS5220M-xxF		GS5220T-xxF								
1	VIN	5	GND	1	VIN	5	GND	1	VIN	5	SD	VIN	VIN	5	SD
2	Vout	6	GND	2	V _{OUT}	6	GND	2	V _{OUT}			2	Vout		
3	FB	7	GND	3	FB	7	GND	3	GND			3	GND		
4	SD	8	GND	4	SD	8	GND	4	FB			4	FB		

PIN Name	Description
V _{IN}	Operating voltage input
V _{OUT}	Switching output
GND	Ground
FB	Output voltage feedback control
SD	ON/OFF Shutdown

Ordering Information



Part Number							
(PDIP-8L)	(SOP-8)	(TO-263-5L)	(TO-220-5L)	Voltage			
GS5220PF	GS5220SF	GS5220MF	GS5220TF	ADJ			
GS5220P33F	GS5220S33F	GS5220M33F	GS5220T33F	3.3			
GS5220P50F	GS5220S50F	GS5220M50F	GS5220T50F	5.0			

*Adjustable Version does not need Voltage Code. **For other voltages, please contact factory

Marking Information





Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage	V _{CC}	+24	V
ON /OFF Pin Input Voltage	V _{SD}	-0.3 to +18	V
Feedback Pin Voltage	V _{FB}	-0.3 to +18	V
Output Voltage to Ground	V _{OUT}	-1	V
Power Dissipation	PD	Internally limited	W
Storage Temperature	T _{ST}	-65 to +150	°C
Operating Temperature	T _{OP}	-40 to +125	°C
Operating Voltage	V _{OP}	+4.5 to +22	V

Electrical Characteristics

Unless otherwise specified ,V_{IH}=12V for 3.3V , 5V , adjustable version and V_{in}=18V for the 12V version. I_{LOAD}=0.5A

Parameter	Symbol	Symbol Conditions		Min	Тур	Max	Unit
		V _{FB}	=1.3V		10	-50	
Feedback Blas Current	IFB	(Adjustable	version only)		-10	-100	nA
Oscillator Frequency	Faaa		_	127	150	173	<u>к</u> п-
Oscillator i requercy	TOSC			110		173	NI IZ
Oscillator Frequency of Short Circuit Protect	F _{SCP}	When current I V _{FB} <0.5	imit occurred and V,Ta=25℃	10	30	50	KHz
Saturation Voltage	V _{SAT}	I _{OUT} =2A No V _{FB} =0V fo	o outside circuit rce driver on		1.4	1.6 1.7	V
Max Duty Cycle (ON)	DC	V _{FB} =0V fo	rce driver on		100		0/
Min Duty Cycle (OFF)	DC	V _{FB} =12V fo	orce driver off		0		/0
Current Limit	I _{CL}	Peak current No outside circuit V _{FB} =0 force driver on		2.5	3.6	5.5 6.5	A
Output=0V Output Leakage	Ŀ	No outside circuit V _{FB} =12 force driver off				-200	uA
Output=1V Current	۱L	V _{IN} =22V			-5		mΑ
Quiescent Current	l _Q	V _{FB} =12 force driver off			5	10	mΑ
Standby Quiescent Current	lame.	ON/OFF pin=5V			70	150	ıιΔ
	ISIBI	V _{IN} =22V			10	200	
ON/OFF Pin Logic Input	VIL	Low (regulator ON)			13	0.6	v
Threshold Voltage	V _H	High (regulator OFF)		2			,
ON/OFF Pin Logic Input Current	I _H	V _{LOGIC} =2.5V (OFF)				-0.01	uA
ON/OFF Pin Input Current	١L	VLOGIC=	0.5V (ON)		-0.1	-1	uA
		TO-220-5L			2.5		
Thermal Resistance Junction	A.o	TO-263-5L	_		3.5		°C AN
to Case	O JC	PDIP-8L	DIP-8L		12		0,00
		SOP-8			20		
		TO-220-5L			28		
Thermal Resistance Junction	A IA	TO-263-5L with copper area of			23		$^{\circ}$ M
to Ambient	OJA	PDIP-8L	approximately 3 in ²		35		0,00
		SOP-8			150		





Part Number	Symbol	Parameter	Conditions	Тур	Limit	Unit
			$5V \leq V_{IN} \leq 22V$			V
CSE220 Adi	V _{FB}	Output Feedback	$0.2A {\leq} I_{LOAD} {\leq} 2A$	1.23	1.193/1.18	V _{MIN}
G55220-Auj			Vout programmed for 3V		1.267/1.28	V _{MAX}
	η	Efficiency	V _{IN} =12V,I _{LOAD} =2A	74		%
	Maxim		$5.5V \leq Vin \leq 22V$	2.2	3.168/3.135	V _{MIN}
GS5220-3.3	VOUI	Output voltage	$0.2A \leq I_{LOAD} \leq 2A$	3.5	3.432/3.465	V _{MAX}
	η	Efficiency	V _{IN} =12V,I _{LOAD} =2A	75		%
	Vaur		8V≦Vin≦22V	Б	4.8/4.75	V _{MIN}
GS5220-5.0	VOUI	Output voltage	$0.2A \leq I_{LOAD} \leq 2A$	5	5.2/5.25	V _{MAX}
	η	Efficiency	V _{IN} =12V,I _{LOAD} =2A	80		%

Electrical Characteristics (Continue)

Typical Applications Circuit (To Packages)





Typical Performance Characteristics



GS5220 Efficiency v.s. Temperature (V_{IN}=12V, V_{OUT}=3.3V, I_O=2A) 78 77 76 75 8 74 Efficiency 73 72 71 70 -30 -10 10 30 50 70 90 110 130 150 -50 Temperature (TA) (°C)

GS5220 Efficiency v.s. Temperature

(V_{CC}=12V, V_{FB}=0V, V_{SD}=0V)



GS5220 Efficiency v.s. Temperature





GS5220 Supply Current v.s. Temperature

(V_{CC} =12V, No Load, V_{ON/OFF} =0V (Switch ON), V_{ON/OFF} =5V (Switch OFF))





Typical Performance Characteristics (Continue)

GS5220



GS5220 ON/OFF Current v.s. ON/OFF Voltage



GS5220 Frequency v.s. Temperature $(V_{CC}=12V, I_{O}=500mA, V_{OUT}=5V)$ 170 10 165 0 (IA) (ZHX) -10 Feedback Current 155 -20 Acuenties 150 -30 -40 140 -50 -50 -30 -10 10 30 50 70 90 110 130 150 Temperature (TA) (°C)

GS5220 Feedback Current v.s. Temperature





GS5220 Output Voltage v.s. Temperature







Function Description

Pin Functions

$+V_{IN}$

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be present at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

Ground

Circuit ground.

Output

Internal switch. The voltage at this pin switches between $(+V_{IN} - V_{SAT})$ and approximately -0.5V, with a duty cycle of approximately V_{OUT} / V_{IN} . To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be kept a minimum.

Feedback (FB)

Senses the regulated output voltage to complete the feedback loop.

ON/OFF (SD)

Allows the switching regulator circuit to be shutdown using logic level signals thus dropping the total input supply current to approximately 150uA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V (up to a maximum of 18V) shuts the regulator down. If this shutdown feature is not needed, the ON/ OFF pin can be wired to the ground pin.

Thermal Considerations

The GS5220 is available in two packages : a 5-pin TO-220 and a 5-pin surface mount TO-263.

The TO-220 package needs a heat sink under most conditions. The size of the heat sink depends on the input voltage, the load current and the ambient temperature .The GS5220 junction temperature rises above ambient temperature for a 2A load and different input and output voltages. The data for these curves was taken with the GS5220(TO-220 package) operating as a buck-switching regulator in an ambient temperature of 25° C (still air). These temperature rise numbers are all approximate and there are many factors that can affect these temperatures. Higher ambient temperatures require more heat sink.

The TO-263 surface mount package tab was designed to be soldering to the copper on a printed circuit board .The copper and the board are the heat sink for this package and the other heat producing components, such as the catch diode and inductor. The PC board copper area that the package is soldered to should be at least 0.8 in², and ideally should have 2 or more square inches of 2 oz. Additional copper area improves the thermal characteristics, but with copper areas greater than approximately 6 in², only small improvements in heat dissipation are realized. If further thermal improvements are needed double sided, multi-layer PC board with large copper areas and/or airflow will be recommended.

The GS5220 (TO-263 package) junction temperature rises above ambient temperature with a 2A load for various input and output voltages. This data was taken with the circuit operating as a buck-switching regulator with all components mounted on a PC board to simulate the junction temperature under actual operating conditions. This curve can be used for a quick check for the approximate junction temperature for various conditions, but be aware that there are many factors that can affect the junction temperature. When load currents higher than 2A are used, double sided or multi-layer PC boards with large copper areas and/or airflow might be needed, especially for high ambient temperatures and high output voltages.

For the best thermal performance .wide copper traces and generous amounts of printed circuit board copper should be used in the board layout.

(Once exception to this is the output(switch) pin, which should not have large areas of copper.) Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

Package thermal resistance and junction temperature rise numbers are all approximate, and there are many factors that will affect these numbers. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are, trace width, total printed circuit copper area, copper thickness, single or double-sided, multi-layer board and the amount of solder on the board. The effectiveness of the PC board to dissipate heat also depends on the size, quantity and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components such as the catch diode will add heat to the PC board and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.



Package Dimension

TO-220-5L PLASTIC PACKAGE



SAMBOI	Dimensions I	n Millimeters	Dimensions In Inches		
STWBOL	MIN	MAX	MIN	MAX	
Α	4.47	4.67	.176	.184	
A1	2.52	2.82	.099	.111	
b	0.71	0.91	.028	.036	
С	0.31	0.53	.012	.021	
c1	1.17	1.37	.046	.054	
D	9.85	10.15	.388	.400	
E	8.20	8.60	.323	.339	
E1	11.76	12.16	.463	.479	
е	1.70	(TYP)	0.067	(TYP)	
e1	6.70	6.90	.264	.272	
F	2.59	2.89	.102	.114	
L	13.50	13.90	.531	.547	
Φ	3.79	3.89	.149	.153	





TO-263-5L PLASTIC PACKAGE



Symbol	Dimensions Ir	n Millimeters	Dimensions In Inches		
Cymbol	Min	Max	Min	Max	
Α	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.560	1.760	0.061	0.069	
b	0.710	0.910	0.028	0.036	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	9.880	10.180	0.389	0.401	
E	8.200	8.600	0.323	0.339	
е	1.700	TYP	0.067TYP		
e1	6.700	6.900	0.264	0.272	
L	15.140	15.540	0.596	0.612	
L1	5.080	5.480	0.200	0.216	
L2	2.340	2.740	0.092	0.108	
V	5.600	REF	0.220	REF	





PDIP-8 PLASTIC PACKAGE







Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	3.710	4.310	.146	.170	
A1	0.510	-	.020	-	
A2	3.200	3.600	.126	.142	
В	0.380	0.570	.015	.022	
B1	1.524	4(BSC)	0.060 (BSC)		
С	0.204	0.360	.008	.014	
D	9.000	9.400	.354	.370	
E	6.200	6.600	.244	.260	
E1	7.320	7.920	.288	.312	
е	2.540(BSC)		.100 (BSC)		
L	3.000	3.600	.118	.142	
E2	8.400	9.000	.331	.354	





$\begin{array}{c|c} \theta 1 \\ \hline \\ \theta 2 \\ \hline \\ \theta 2 \\ \hline \\ R \\ \hline \\ R \\ \hline \\ R \\ GAUGE \\ PLANE \\ \hline \\ L2 \\ \hline \\ \\ H \\ \hline \\ H \\$

Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	1.35	1.75	.053	.069	
A1	0.10	0.25	.004	.010	
A2	1.25	1.65	.049	.065	
b	0.31	0.51	.012	.020	
С	0.17	0.25	.007	.010	
D	4.90	(TYP)	.193 (TYP)		
E	E 6.00 (TYP)		.236 (TYP)		
E1	3.90	(TYP)	.154 (TYP)		
е	1.27	(TYP)	.050	(TYP)	
L	0.40	1.27	.016	.050	
L1	1.04	(TYP)	.041	(TYP)	
L2	0.25	(TYP)	.010	(TYP)	
R	0.07	-	.003	-	
R1	0.07	-	.003	-	
h	0.25	0.50	.010	.020	
θ	0°	8°	0°	8°	
θ1	5°	15°	5°	15°	
θ2	0°	-	0°	-	

SOP-8 PLASTIC PACKAGE





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(Revise Date:2007/11/13 Version_1.0)

